



ELECTROLESS COPPER PLATING PRODUCTS



Commodity Name

HN-660 ELECTROLESS COPPER



Bath Composition and Working Conditions

Electroless Copper Additive HN-660A	75 mL /L
Electroless Copper Additive HN-660M	50 mL /L
Electroless Copper Additive HN-660B	80 mL /L
Copper Ion	2.1 ~3.0 g/L
Sodium Hydroxide	10 ~14 g/L
Methanol	3.0 ~5.0 g/L
Temperature	20 ~27 °C
Charge Capacity	0.8 ~2.8 dm ² /L
Agitation	Proper air agitation
Filtration	Continuous overflow filtration



Application and Advantage

1. The layer has fine grained structure and good adhesion.
2. The bath solution is stable and is easy to control.



广东高力集团
HIGHNIC GROUP

 **广东致卓精密金属科技有限公司**
SUR-PRECISION METAL TECHNOLOGY CO., LTD.

- Production Base : Central Part of Non-ferrous Metal Industrial Development Zone, Shishan, Nanhai, Foshan, Guangdong, China
- Sales Center : Highnic Group Building, Guangfo Rd., Yanbu, Dali Town, Nanhai District, Foshan City, Guangdong Province, China.
- Mail: sale@imt-pcb.com Fax : (86-757) 85768678 Tel: (86-757) 85728852